



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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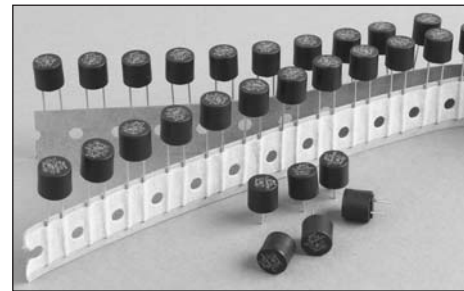
Subminiature Fuses

SR-5F Series, Fast-Acting



Description

- Fast-acting, low breaking capacity subminiature fuse
- Plastic cap and base, flammability UL 94V0
- Lead wire with tin-plated copper, diameter 0.6mm
- Protects against harmful overcurrents in primary and secondary applications
- Small radial-leaded design minimizes board space and eliminates need for additional mounting components (BK/PCS holder optional if field replacement is desirable)
- Designed to UL 248-14



Electrical Characteristics			
Rated Current	1 x I _n min	1.5 x I _n max	2 x I _n max
800mA-10A	4hr	10 min	2 min

Agency Information

- UL Listed: File E19180 JDXY1, JDYX7
- PSE: File JET5766-31007-1001, File JET5766-31007-1002

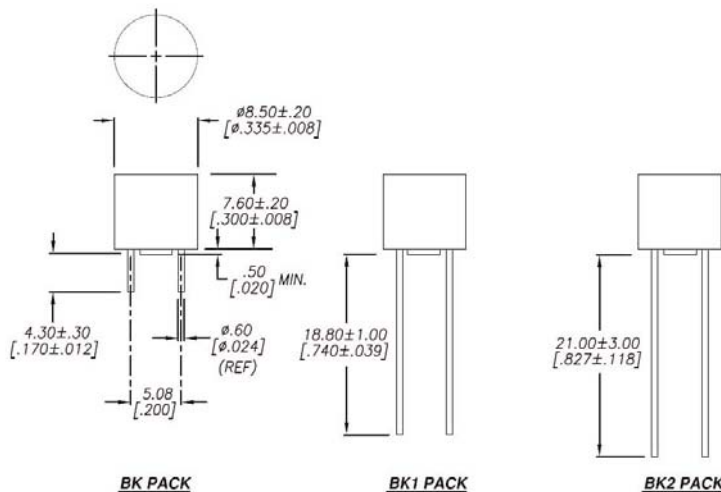
Specifications

- Solderability: EIA-186-9E Method 9
- High frequency vibration: MIL-STD-202F, Method 201A
- Operating temperature: -40°C to +125°C
- Soldering heat resistance: 260°C, 10 sec. max. (IEC 60068-2-20)

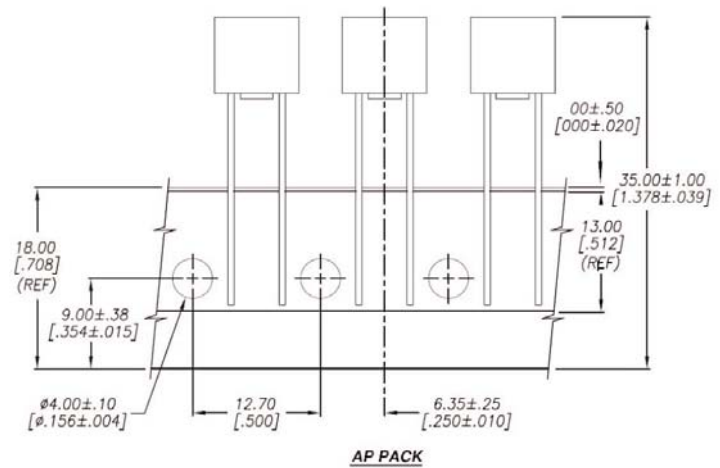
Ordering

- Specify product and packaging code (i.e., SR-5F-1A-AP)

Dimensions - mm / [inches]



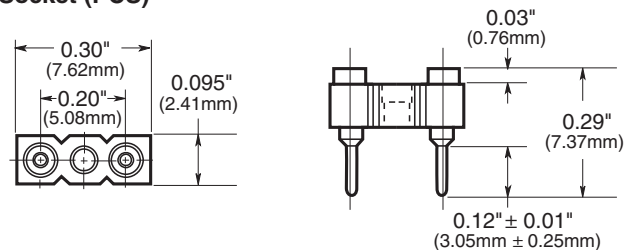
Packaging - mm / [inches]



Mounting Socket (RoHS compliant)

- Available as option. Specify catalog number BK/PCS (In bulk 100 per bag)

Socket (PCS)



Specifications

Catalog Number	Voltage Rating (Vac)	Interrupting Rating (amps) @ Rated Voltage (50Hz)**	Typical DC Cold Resistance (Ω)***	Typical Melting I ² t†	Maximum Voltage Drop@1I _n (mV)‡	Maximum Power Dissipation @ 1In(mW)†††	Agency Approvals	
							cULus	PSE
SR-5F-800mA	250	50	0.245	1.5	400	320	X	
SR-5F-1A	250	50	0.171	2.6	400	400	X	X
SR-5F-1.25A	250	50	0.116	4.4	330	413	X	X
SR-5F-1.6A	250	50	0.076	6.9	330	528	X	X
SR-5F-2A	250	50	0.058	9	330	660	X	X
SR-5F-2.5A	250	50	0.049	15	330	825	X	X
SR-5F-3.15A	250	50	0.037	23.2	330	1040	X	X
SR-5F-4A	250	50	0.026	35.4	330	1320	X	X
*SR-5F-5A	250	50	0.018	55	250	1250	X	X
*SR-5F-6.3A	125	50	0.015	75	250	1575	X	X
*SR-5F-7A	125	50	0.011	107	250	1750	X	X
*SR-5F-8A	125	50	0.010	120	200	1600	X	X
*SR-5F-10A	125	50	0.007	145	200	2000	X	X

*Conducting path min. 0.2mm²

**Interrupting ratings measured at 50A, 95%-100% of PF on AC.

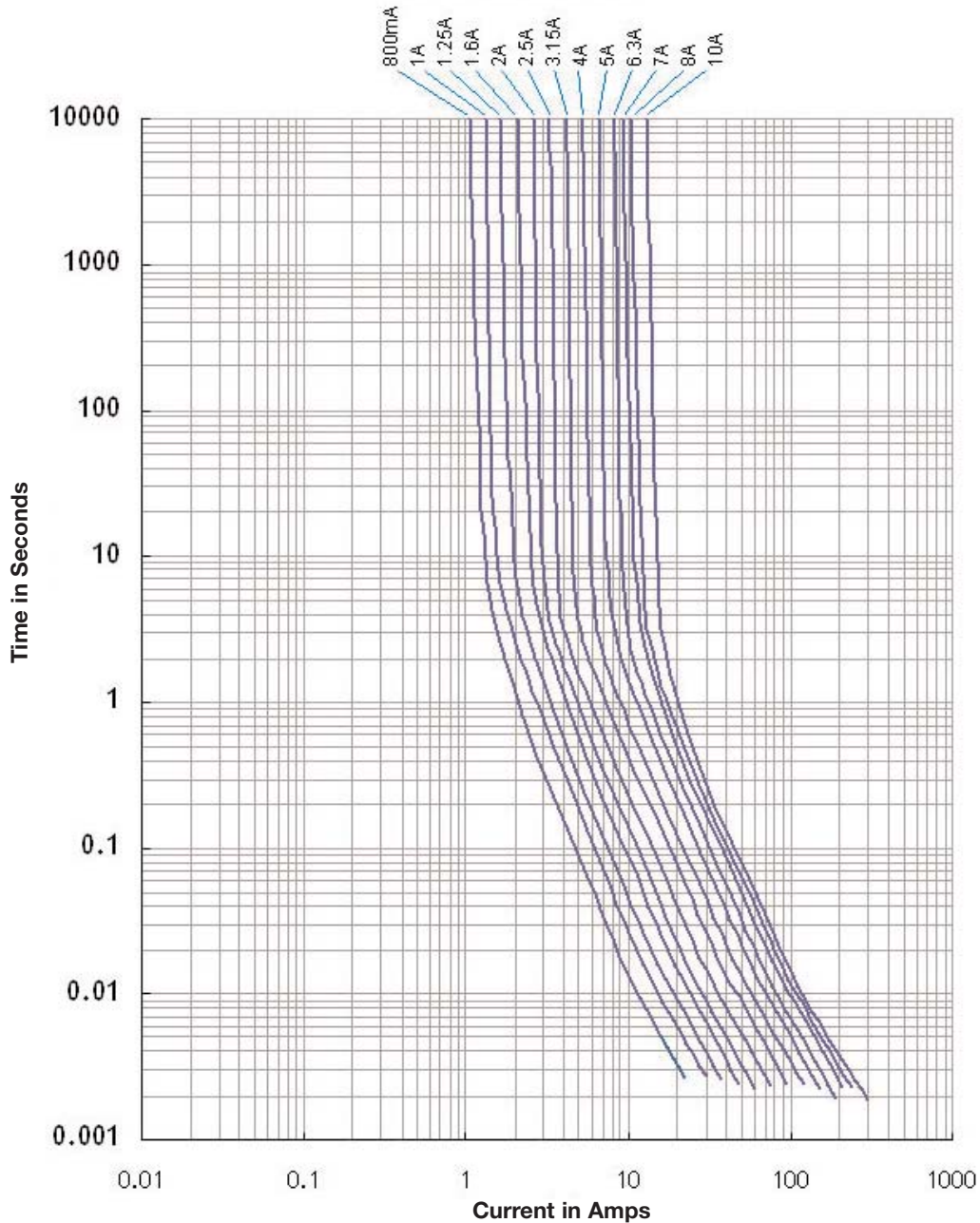
***Typical DC Cold Resistance measured at <10% of rated current.

†Typical Melting I²t measured at 10I_n.

‡ Maximum Voltage Drop measured at 20°C ambient temperature at rated current.

†††Maximum Power Dissipation measured at 20°C ambient temperature at rated current.

Time-Current Curve



Packaging Code	
Packaging Suffix	Description
-BK	200 fuses in polybag, Lead L = 4.3 ± 0.3
-BK1	200 fuses in polybag, Lead L = 18.8 ± 1.0
-BK2	200 fuses in polybag, Lead L = 21 ± 3.0
-AP	1000 fuses Ammo Pack, Pitch = 12.7

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